

Substrate: 3.18mm  $\pm$ 0.25mm [0.125"  $\pm$ 0.001"] FR4/G10 or equivalent high temp material. 17 $\mu$ m [1/2 oz.] Cu clad. SnPb plating.




Solder ball: Eutectic Sn63Pb37

**Description:** BGA Surface Mount Adaptor

121 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>SF-BGA121D-B-05 Drawing</b>		Status: Released	Scale: 3:1	Rev: B
 <p>© 2002 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: H. Hansen		Date: 8/14/02	
	File: SF-BGA121D-B-05 Dwg		Modified: 6/15/05	